

Working parameters

- Use at least 1.5 % MEKP
- Working temperature between 18-24 °C
- The surface should be clean and free of grease and dust
- Low resin surface in bonding area
- Sand the substrate before bonding
- Prime wood and metals

Your advantages

- High-strength bonding of different materials
- High fatigue strength, impact resistance and elongation at break
- Promotes processing (levelling, round edges)
- Optimal surface quality through low-shrink systems
- Reduction of weight, vibrations and noise